

TPS53689 Dual-channel ($N + M \leq 8$ phase) D-CAP+™, Step-down, Multiphase Controller with PMBus and VR14 SVID Interfaces

1 Features

- Input voltage range: 4.5 V to 17 V
- Output voltage range: 0.25 V to 5.5 V
- Dual output supporting N+M phase configurations ($N+M \leq 8$, $M \leq 4$)
- Intel® VR14 SVID compliant with PSYS support
- Backward compatible to VR13.HC/VR13.0 SVID
- Automatic NVM fault status logging
- Dynamic current limit for improved Fast-Vmode performance
- Fully compatible with TI NexFET™ power stage for high-density solutions
- Enhanced D-CAP+ control to provide superior transient performance with excellent dynamic current sharing
- Dynamic phase shedding with programmable thresholds for optimizing efficiency at light and heavy loads
- Configurable with non-volatile memory (NVM) for low external component count
- Accurate, adjustable, adaptive voltage positioning (AVP, load line) support
- Individual per-phase IMON calibration, with multi-slope gain calibration to increase system accuracy.
- Fast phase-adding for transient undershoot reduction
- Diode braking with programmable timeout for reduced transient overshoot
- Patented AutoBalance™ current sharing
- Programmable per-phase valley current limit (OCL)
- PMBus™ v1.3.1 system interface for telemetry of voltage, current, power, temperature, and fault conditions
- Programmable loop compensation through PMBus
- Driverless configuration for efficient high-frequency switching
- 5.00 mm × 5.00 mm, 40-pin, QFN package

2 Applications

- [Data center & enterprise computing rack server](#)
- [Hardware accelerator](#)
- [Network interface card \(NIC\)](#)
- ASIC and [high performance client](#)

3 Description

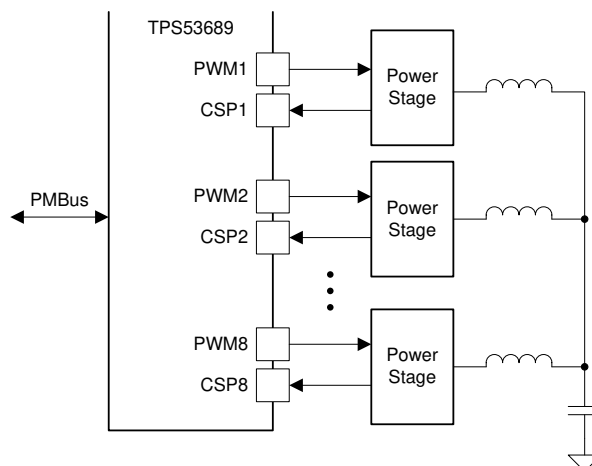
The TPS53689 is a VR14 SVID compliant step down controller with two channels, built-in non-volatile memory (NVM), and PMBus™ interface, and is fully compatible with TI NexFET™ power stages. Advanced control features such as the D-CAP+ architecture with undershoot reduction (USR) and overshoot reduction (OSR) provide fast transient response, low output capacitance, and good dynamic current sharing. The device also provides novel phase interleaving strategy and dynamic phase shedding for efficiency improvement at different loads. Adjustable control of output voltage slew rate and adaptive voltage positioning are natively supported. In addition, the device supports the PMBus communication interface for reporting the telemetry of voltage, current, power, temperature, and fault conditions to the host system. All programmable parameters can be configured through the PMBus interface and can be stored in NVM as the new default values, to minimize the external component count.

The TPS53689 device is offered in a thermally enhanced 40-pin QFN packaged and is rated to operate from -40°C to 125°C .

Device Information

PART NUMBER	PACKAGE ⁽¹⁾	BODY SIZE (NOM)
TPS53689	QFN (40)	5.00 mm × 5.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Simplified Application



4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
June 2021	*	Initial release.

5 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

5.1 Documentation Support

5.1.1 Related Documentation

5.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

5.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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5.4 Trademarks

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5.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.



5.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS53689RSBR	ACTIVE	WQFN	RSB	40	3000	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	TPS 53689	
TPS53689RSBT	ACTIVE	WQFN	RSB	40	250	RoHS & Green	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	TPS 53689	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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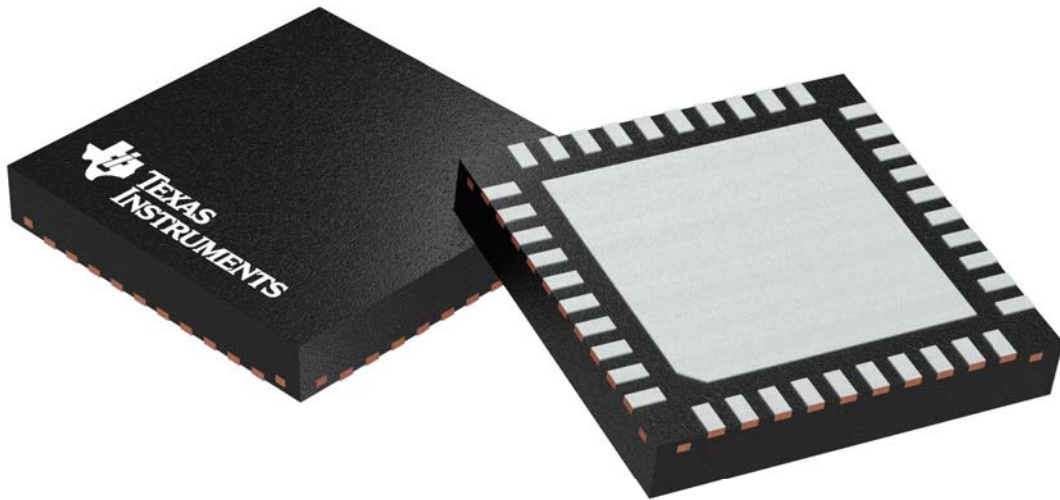
GENERIC PACKAGE VIEW

RSB 40

WQFN - 0.8 mm max height

5 x 5 mm, 0.4 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

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